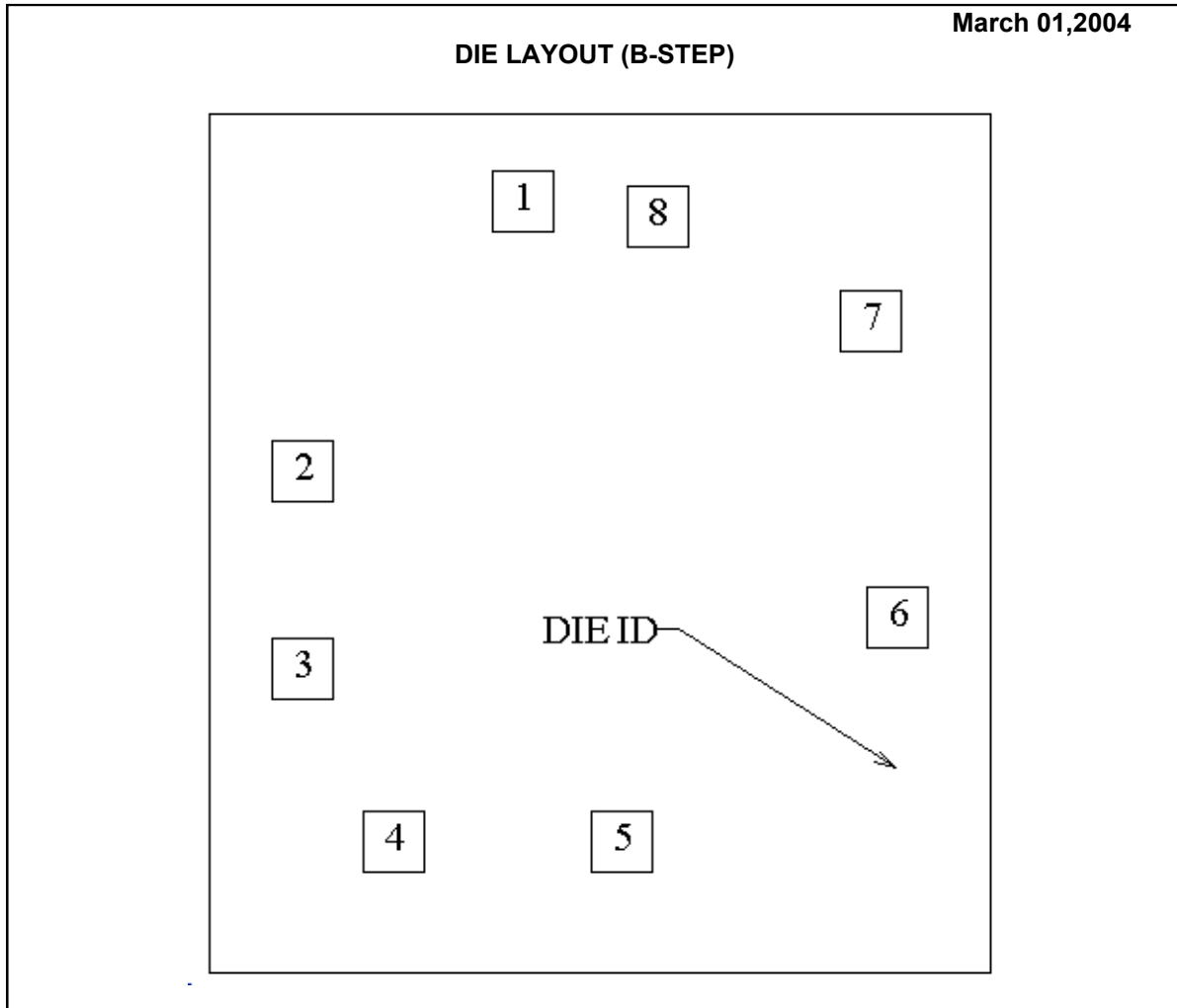


**LM1949 MDC MWC
INJECTOR DRIVE CONTROLLER**



DIE/WAFER CHARACTERISTICS

Fabrication Attributes		General Die Information	
Physical Die Identification	LM1949B	Bond Pad Opening Size (min)	114µm x 115µm
Die Step	B	Bond Pad Metalization	ALUMINUM
Physical Attributes		Passivation	VOM NITRIDE
Wafer Diameter	150mm	Back Side Metal	BARE BACK
Die Size (Drawn)	1473µm x 1626µm 58.0mils x 64.0mils	Back Side Connection	Floating
Thickness	406µm Nominal		
Min Pitch	254µm Nominal		

Special Assembly Requirements:

Note: Actual die size is rounded to the nearest micron.

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Die Bond Pad Coordinate Locations (B -Step)						
(Referenced to die center, coordinates in μm) NC = No Connection, N.U. = Not Used						
SIGNAL	PAD#	XY COORDINATES		PAD SIZE		
NAME	NUMBER	X	Y	X	Y	
INPUT	1	-146	647	115	x	115
OUTPUT	2	-563	137	114	x	115
COMP	3	-562	-238	115	x	115
SENSE	4	-390	-563	114	x	115
SUPPLY GND	5	42	-563	115	x	115
GND	6	562	-141	115	x	115
VCC	7	513	419	115	x	114
TIMER	8	108	617	115	x	115

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